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Substitute for form 1449A/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  <i>(use as many sheets as necessary)</i>				<i>Complete if Known</i>	
				Application Number	
				Filing Date	
				First Named Inventor	
				Group Art Unit	
				Examiner Name	
Sheet	1	of	2	Attorney Docket Number	SC11852HP

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Examiner Signature	Luan Thai	Date Considered	01/11/03
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		Application Number	
		Filing Date	
		First Named Inventor	MAN HON CHENG
		Group Art Unit	
		Examiner Name	
Sheet 2	of 2	Attorney Docket Number	SC11852HP

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OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
	3	NATIONAL SEMICONDUCTOR CORPORATION, Semiconductor Packaging Assembly Technology, August 1999	
	4	NATIONAL SEMICONDUCTOR CORPORATION, Plastic Package Moisture-Induced Cracking, August 1999	
	5	RUIHUA HAN, LINHUO SHI, AND MAHESH GUPTA, Three-Dimensional Simulation of Microchip Encapsulation Process, Department of Mechanical Engineering-Engineering Mechanics, Michigan Technological University, Houghton, Michigan 49931	

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